

# 2SK3287

Silicon N Channel MOS FET  
High Speed Switching

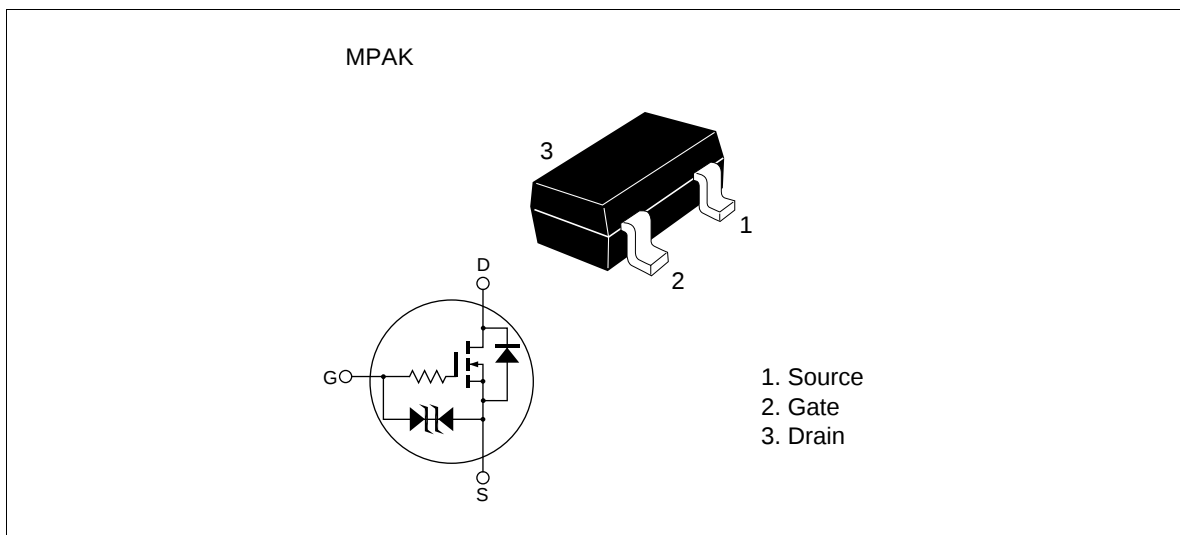
# HITACHI

ADE-208-742 C (Z)  
4th.Edition.  
June 1999

## Features

- Low on-resistance  
 $R_{DS} = 1.26 \Omega$  typ. ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 150 \text{ mA}$ )  
 $R_{DS} = 2.8 \Omega$  typ. ( $V_{GS} = 4 \text{ V}$ ,  $I_D = 50 \text{ mA}$ )
- 4 V gate drive device.
- Small package (MPAK)

## Outline



## 2SK3287

### Absolute Maximum Ratings (Ta = 25°C)

| Item                                   | Symbol                           | Ratings     | Unit |
|----------------------------------------|----------------------------------|-------------|------|
| Drain to source voltage                | $V_{DSS}$                        | 30          | V    |
| Gate to source voltage                 | $V_{GSS}$                        | $\pm 20$    | V    |
| Drain current                          | $I_D$                            | 300         | mA   |
| Drain peak current                     | $I_{D(pulse)}$ <sup>Note 1</sup> | 1.2         | A    |
| Body-drain diode reverse drain current | $I_{DR}$                         | 300         | mA   |
| Channel dissipation                    | $P_{ch}$ <sup>Note 2</sup>       | 400         | mW   |
| Channel temperature                    | $T_{ch}$                         | 150         | °C   |
| Storage temperature                    | $T_{stg}$                        | -55 to +150 | °C   |

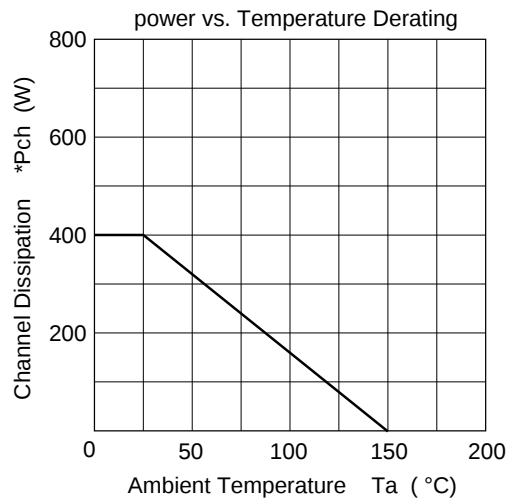
Note: 1.  $PW \leq 10 \mu s$ , duty cycle  $\leq 1\%$   
2. Value on the alumina ceramic board (12.5 x 20 x 0.7 mm)

### Electrical Characteristics (Ta = 25°C)

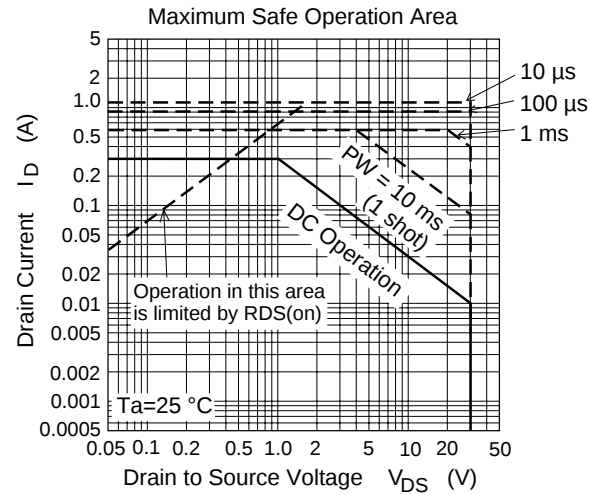
| Item                                       | Symbol        | Min      | Typ  | Max     | Unit     | Test Conditions                                    |
|--------------------------------------------|---------------|----------|------|---------|----------|----------------------------------------------------|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 30       | —    | —       | V        | $I_D = 100 \mu A$ , $V_{GS} = 0$                   |
| Gate to source breakdown voltage           | $V_{(BR)GSS}$ | $\pm 20$ | —    | —       | V        | $I_G = \pm 100 \mu A$ , $V_{DS} = 0$               |
| Gate to source leak current                | $I_{GSS}$     | —        | —    | $\pm 5$ | $\mu A$  | $V_{GS} = \pm 16 V$ , $V_{DS} = 0$                 |
| Zero gate voltage drain current            | $I_{DSS}$     | —        | —    | 1       | $\mu A$  | $V_{DS} = 30 V$ , $V_{GS} = 0$                     |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 1.3      | —    | 2.3     | V        | $I_D = 10 \mu A$ , $V_{DS} = 5 V$                  |
| Static drain to source on state resistance | $R_{DS(on)}$  | —        | 1.26 | 1.44    | $\Omega$ | $I_D = 150 mA$ , $V_{GS} = 10 V$ <sup>Note 3</sup> |
|                                            | $R_{DS(on)}$  | —        | 2.8  | 3.44    | $\Omega$ | $I_D = 50 mA$ , $V_{GS} = 4 V$ <sup>Note 3</sup>   |
| Forward transfer admittance                | $ y_{fs} $    | 145      | 220  | —       | mS       | $I_D = 150 mA$ , $V_{DS} = 10 V$ <sup>Note 3</sup> |
| Input capacitance                          | $C_{iss}$     | —        | 6    | —       | pF       | $V_{DS} = 10 V$                                    |
| Output capacitance                         | $C_{oss}$     | —        | 18   | —       | pF       | $V_{GS} = 0$                                       |
| Reverse transfer capacitance               | $C_{rss}$     | —        | 2    | —       | pF       | $f = 1 MHz$                                        |
| Turn-on delay time                         | $t_{d(on)}$   | —        | 200  | —       | ns       | $I_D = 150 mA$ , $V_{GS} = 10 V$                   |
| Rise time                                  | $t_r$         | —        | 600  | —       | ns       | $R_L = 66.6 \Omega$                                |
| Turn-off delay time                        | $t_{d(off)}$  | —        | 1100 | —       | ns       |                                                    |
| Fall time                                  | $t_f$         | —        | 1100 | —       | ns       |                                                    |

Note: 3. Pulse test  
4. Marking is AN

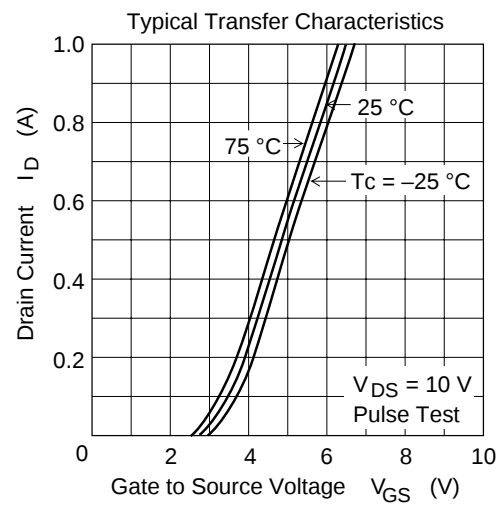
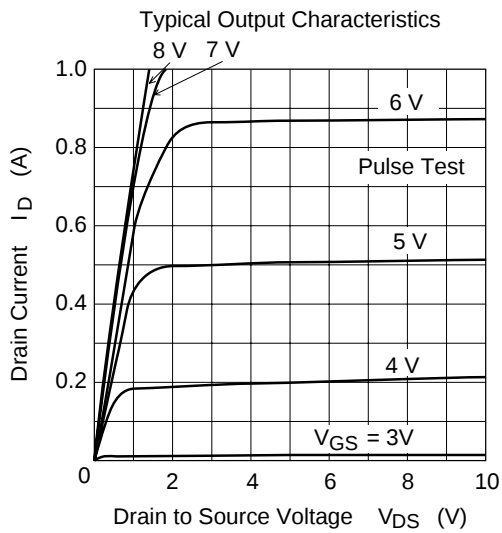
## Main Characteristics



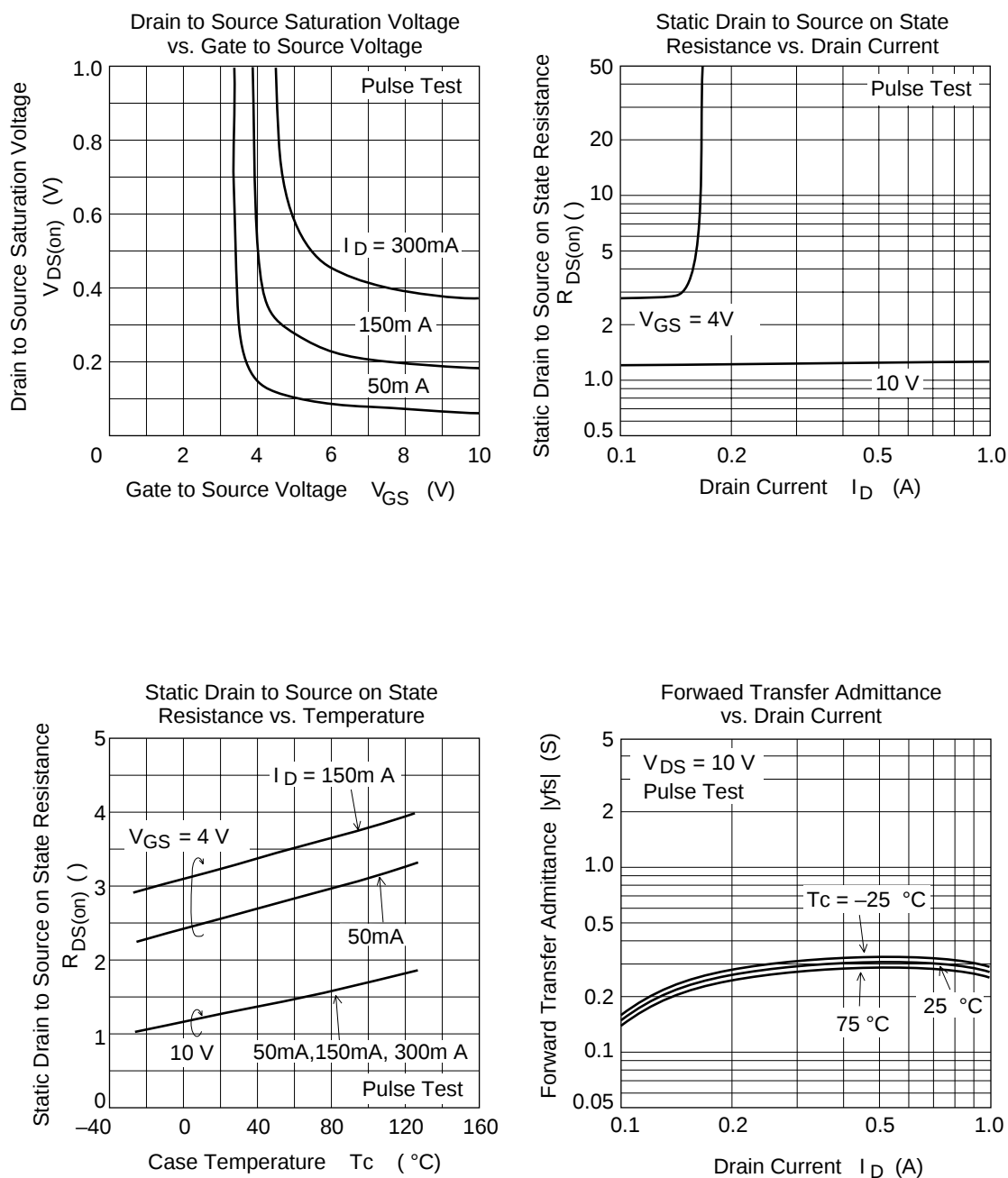
\*Value on the alumina ceramic board.(12.5x20x0.7mm)

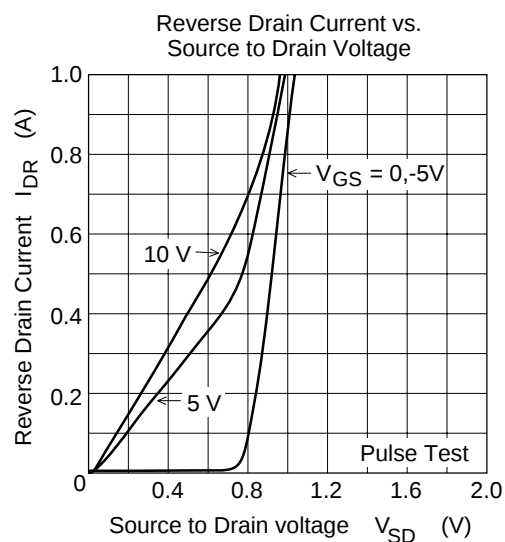
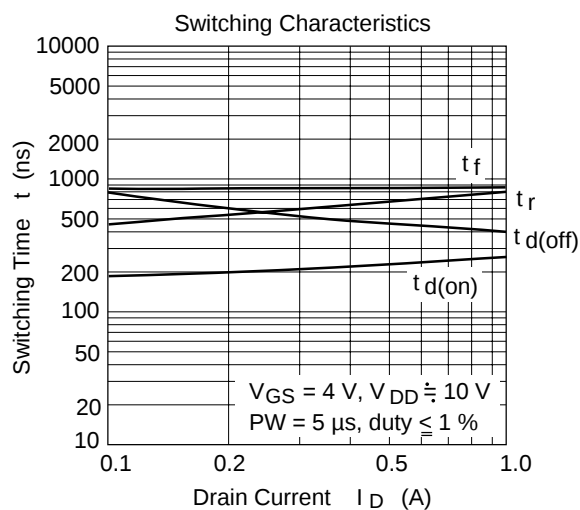
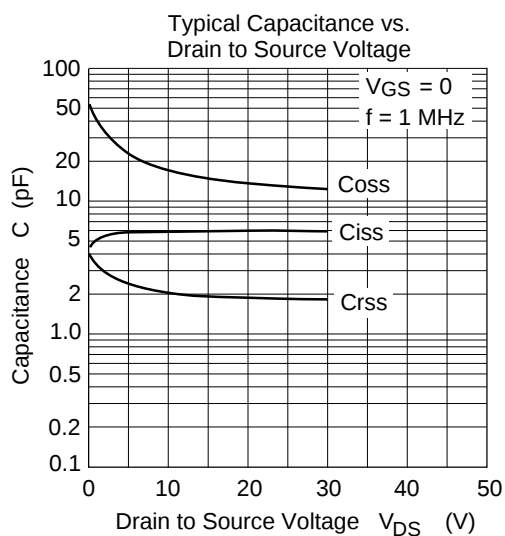


Value on the alumina ceramic board.(12.5x20x0.7mm)

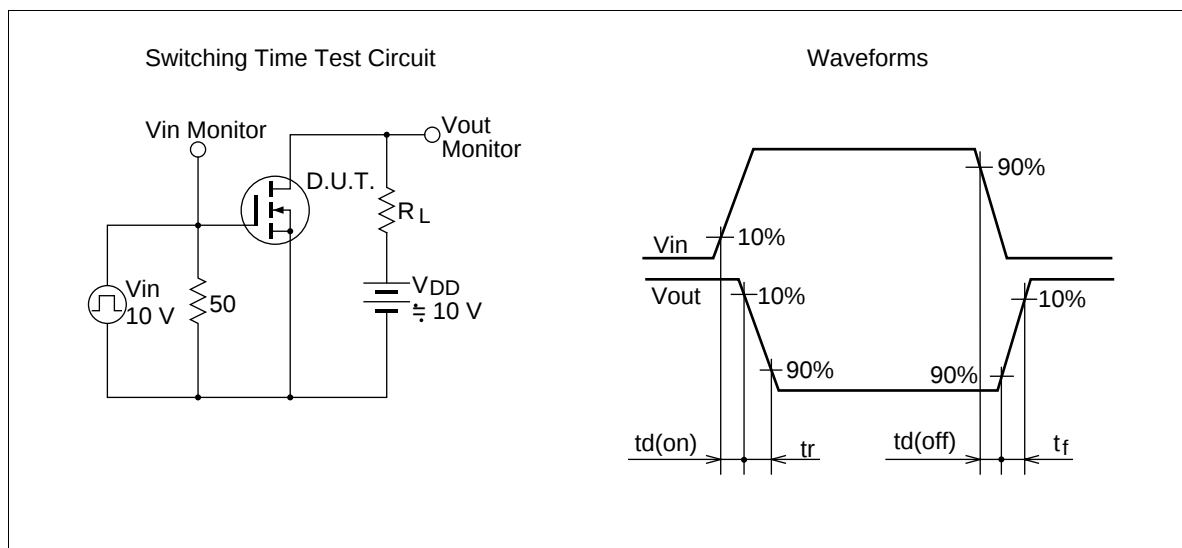


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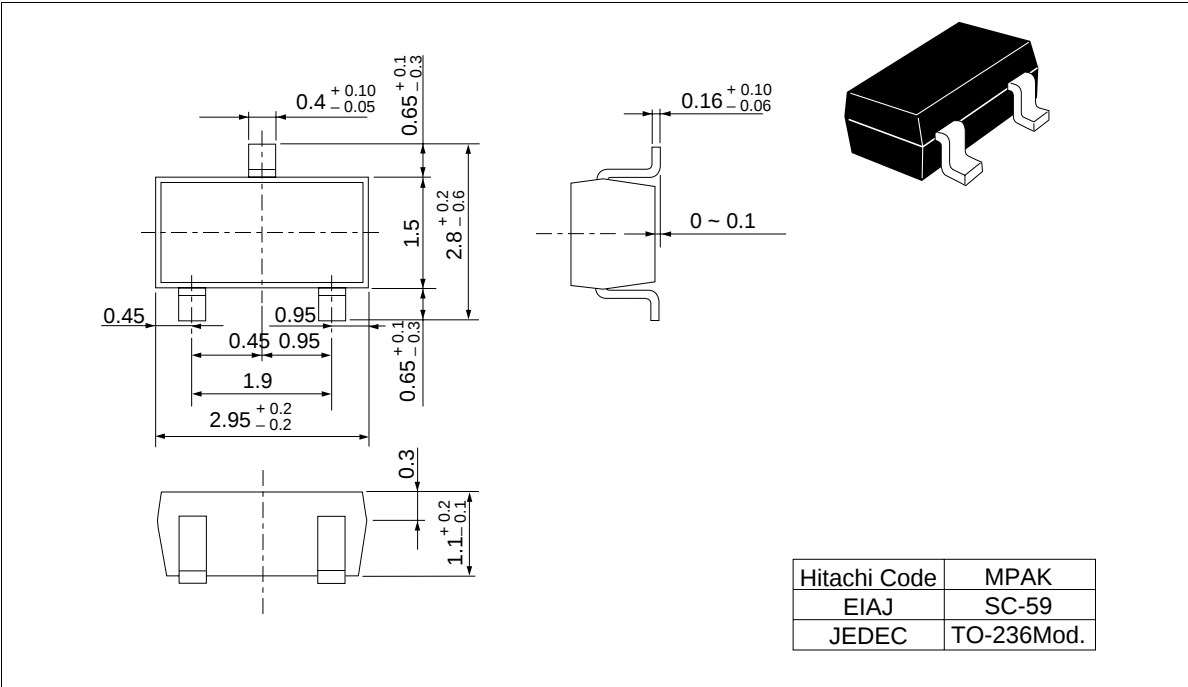


## 2SK3287



Package Dimensions

Unit: mm



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